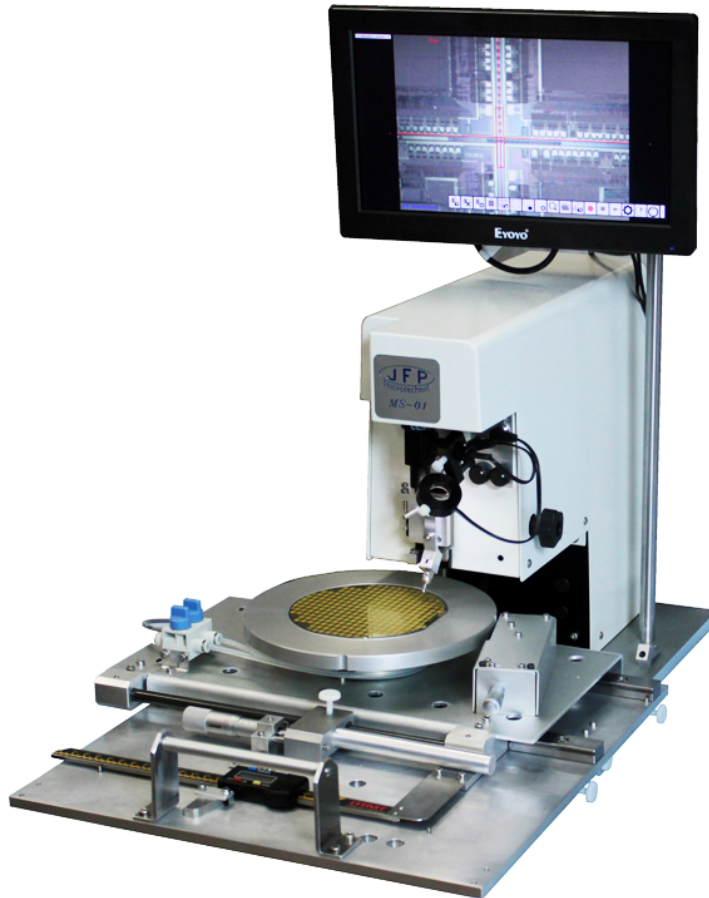


Model MS-1

8" WAFER SCRIBER



APPLICATIONS

- ❖ Thin Glass
- ❖ Borosilicate
- ❖ Silicon
- ❖ GaAs
- ❖ Alumina
- ❖ Sapphire

The MS-1 manual scribe system is a stable, accurate, fast and low cost scribing and cleaving solution suitable for any lab. The system is carrying out a Video Interface compatible for Ultra-HD Camera, with adjustable digital magnification for flexibility, small and large chip sizes. The True vertical motion achieves high accuracy capability bringing scribe line into street < 10 μ m.

Specifications	
MODEL	MS-1 Scribe system
System	<p>Table Top machine,. Compact system Z movement: safe manual drive system. True Vertical motion No height adjustment for thickness: 0-9mm True vertical Vision, Ultra-HD Camera, Soft touch-down Scribe Force: adjustable Throat: 200mm, Access for large substrates</p> <p>FEATURES/PARAMETERS Low Scribing Force: <10 g Diamond tool shank: 1/8 (3,17mm) Lubrication : Automatic,</p>
Work stage	<p>Wafer hold by Vacuum, Substrate, size Up to 200 mm Manually handled Full Scribe travel up to 200mm Rotary base for easy Theta adjustments Fine Theta adjustment by micrometer Internal vacuum Pump Scribe length: 0 mm to 200mm Preset-Tool Holders: Toe and Heal Cut Angle</p>
Application	<p>Glass, ceramic, silicon.... Dots, short marking Full scribe line, ... Inspection/Process HD side Camera</p>
Vision & Alignment	<p>V5M: Camera 5MP, Ultra-HD, Zoom Full Field of view: Up to 11mm also available FOV=25mm Digital Crosshairs, adjustable Adjustable digital video Box Direct Digital Video measure, in μm unit Adjustable Zoom LED lightings coaxial and oblique Display Monitor 12", 1370x770</p>
UTILITIES	<ul style="list-style-type: none"> • Power 100Vac to 230Vac / 50W • Vacuum: 60% • Air:70psiVacuum:60% • Dimensions:450x700x500mm (18"x28"x20") • Weight:70kgr